# 2SB1463

## Silicon PNP epitaxial planer type

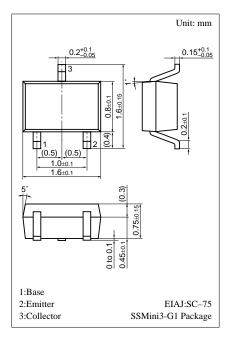
For high breakdown voltage low-noise amplification Complementary to 2SD2240

#### Features

- High collector to emitter voltage V<sub>CEO</sub>.
- Low noise voltage NV.
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

### Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	-150	V
Collector to emitter voltage	$V_{CEO}$	-150	V
Emitter to base voltage	V <sub>EBO</sub>	-5	V
Peak collector current	$I_{CP}$	-100	mA
Collector current	$I_{C}$	-50	mA
Collector power dissipation	$P_{C}$	125	mW
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	$T_{\rm stg}$	<b>−55 ~ +125</b>	°C



Marking symbol: I

#### Electrical Characteristics (Ta=25°C)

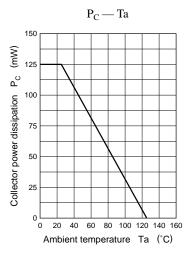
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = -100V, I_{E} = 0$			-1	μΑ
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = -100 \mu A, I_{\rm B} = 0$	-150			V
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = -10\mu A, I_{\rm C} = 0$	-5			V
Forward current transfer ratio	h <sub>FE</sub> *	$V_{CE} = -5V, I_{C} = -10mA$	130		450	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = -30 {\rm mA}, \ I_{\rm B} = -3 {\rm mA}$			-1	V
Transition frequency	$f_T$	$V_{CB} = -10V$ , $I_E = 10mA$ , $f = 200MHz$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10V, I_E = 0, f = 1MHz$		4		pF
Noise voltage	NV	$V_{CE} = -10V, I_{C} = -1mA, G_{V} = 80dB,$	150			mV
		$R_g = 100k\Omega$ , Function = FLAT				

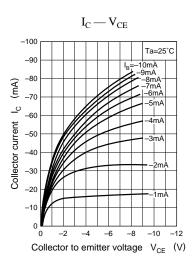
#### \*h<sub>FE</sub> Rank classification

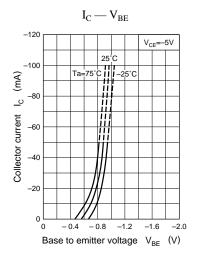
Rank	R	S	T
$h_{\mathrm{FE}}$	130 ~ 220	185 ~ 330	260 ~ 450
Marking Symbol	IR	IS	IT

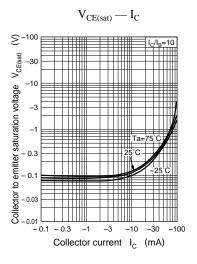
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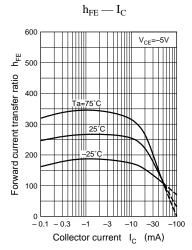
Transistor 2SB1463

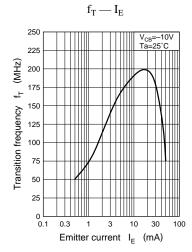


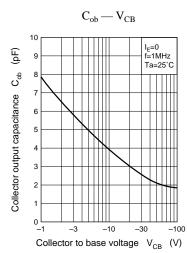












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